

Abstract

A method of forming a low dielectric constant structure. The method comprises providing at
5 a first temperature a dielectric material having a first dielectric constant and a first elastic
modulus, and curing the dielectric material by a thermal curing process, in which the
material is heated to a second temperature by increasing the temperature at an average rate of
at least 1 °C per second. As a result a densified, dielectric material is obtained which has a
low dielectric constant.